

#11/1/10  
PATENT  
2185-0599P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: TAKASHIMA, Masayuki et al. Conf.:  
Appl. No.: NEW Group:  
Filed: December 21, 2001 Examiner:  
For: POLISHING PAD, POLISHING APPARATUS AND  
POLISHING METHOD USING THE SAME

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, DC 20231

December 21, 2001

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

IN THE SPECIFICATION:

Please replace the paragraph beginning on page 2, line 1, with the following rewritten paragraph:

--In conventional CMP of a metal film, it is general to conduct polishing while feeding a polishing slurry containing abrasive particles into between a polishing subject and a polishing pad. However, in this method, the surface of a metal film is scratched and roughened, abrasive are embedded in a metal film, and